SLOVENSKI STANDARD
oSIST prEN IEC 60115-8-10:2026

01-februar-2026

Fiksni upori za uporabo v elektronski opremi - 8-10. del: Neizpolnjena podrobna specifikacija - Površinsko montirani (SMD) tankoplastni upori nizke moči za montažo na tiskana vezja, za univerzalno elektronsko opremo, razvrstitvena raven G

Fixed resistors for use in electronic equipment - Part 8-10: Blank detail specification: Surface mount (SMD) low-power film resistors for assembly on circuit boards, for general electronic equipment, classification level G

Résistances fixes utilisées dans les équipements électroniques - Partie 8-10: Spécification particulière-cadre: Résistances à couche, à faible dissipation, pour montage en surface (CMS) pour assemblage sur cartes de circuit imprimé pour des équipements électroniques généraux, niveau de classification G

Ta slovenski standard je istoveten z: **prEN IEC 60115-8-10:2025**

ICS:

31.040.10	Fiksni upor	Fixed resistors

oSIST prEN IEC 60115-8-10:2026 **en**

40/3264/CDV

COMMITTEE DRAFT FOR VOTE (CDV)

PROJECT NUMBER: **IEC 60115-8-10 ED1**	
DATE OF CIRCULATION: **2025-12-05**	CLOSING DATE FOR VOTING: **2026-02-27**
SUPERSEDES DOCUMENTS: **40/3215/CD, 40/3246/CC**	

IEC TC 40 : CAPACITORS AND RESISTORS FOR ELECTRONIC EQUIPMENT	
SECRETARIAT: Netherlands	SECRETARY: Mr Ronald Drenthen
OF INTEREST TO THE FOLLOWING COMMITTEES:	HORIZONTAL FUNCTION(S):
ASPECTS CONCERNED:	
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TITLE:

Fixed resistors for use in electronic equipment - Part 8-10: Blank detail specification: Surface mount (SMD) low-power film resistors for assembly on circuit boards, for general electronic equipment, classification level G

PROPOSED STABILITY DATE: 2032

NOTE FROM TC/SC OFFICERS:

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIXED RESISTORS FOR USE IN ELECTRONIC EQUIPMENT –

Part 8-10: Blank detail specification: Surface mount (SMD) low-power film resistors for assembly on circuit boards, for general electronic equipment, classification level G

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IEC 60115-8-10 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment. It is an International Standard.

This first edition cancels and replaces IEC 60115-8-1:2014. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) it supports solderability testing for both traditional lead-bearing soldering and up-to-date lead-free soldering, as required;
b) it supports the provision of detailed visual acceptance criteria;
c) it includes the requirement for a visual examination of the primary and proximity packaging;